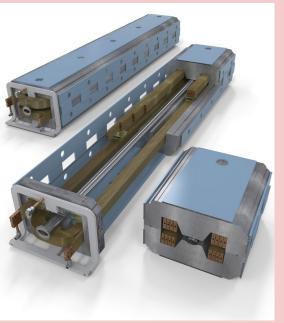
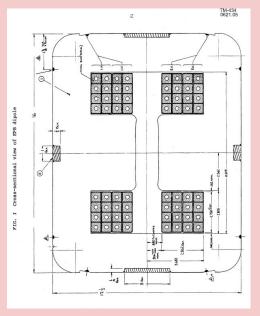


CPS at Hall-D.

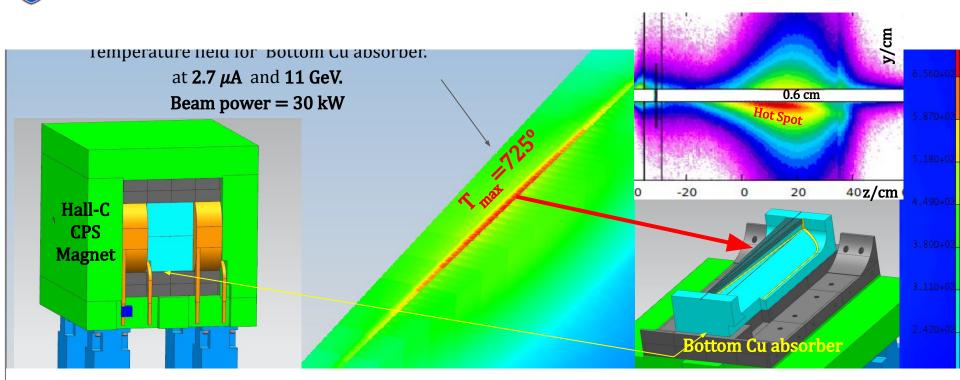
Why we need 3 m long Dipole.



 $p(\gamma, K_0)\Sigma^+$, $n(\gamma, K_0)\Lambda$, $n(\gamma, K_0)\Sigma_0$



Hot Spot Temperature for CPS design from HALL-C .

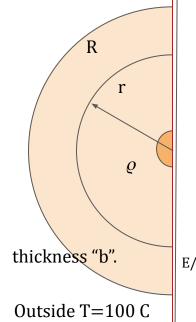


- In this design WCu alloy between coils is replaced with Cu.
- Do we expect **twice higher temperature** at beam power **60 kW**?
- How can we **respond to potential challenge**?



Hot spot Temperature vs Energy Deposition in simple models of copper Disk and Bar.

Heating of $\frac{1}{4}$ Disk by e-beam I=5 μ A, 12 GeV, hot spot radius ρ = 0.25 cm.



Energy deposition rate inside the ¼-disk as in Reference design: sector $\varphi = \frac{1}{4} 2\pi$. dE/dt = b dE/dzdt , where dE/dz is energy deposition of secondaries in Hot Spot. For energy balance in stationary case at heat conductivity \varkappa we write : dE/dt = b dE/dzdt= - φ rb \varkappa dT/dr => dE/dzdt= - φ r \varkappa dT/dr => dT/dr = -(φ \varkappa)⁻¹ dE/dzdt r⁻¹ ; integrate over r < R, T(R)-T(r) = - (φ \varkappa)⁻¹ dE/dzdt ln(R/ ϱ), T(ϱ)=T(R) + (φ \varkappa)⁻¹ dE/dzdt ln(R/ ϱ). Assume realistic ϱ =0.25 cm and R=100 cm. Copper \varkappa =3.98 [W/cm•K]; (Al = 2.4, Brass = 1.1 [W/cm•K]) <= Why using copper!

• For reference design $dE/dV/e = 2.3 [GeV/cm^3/e]$

E/dVdt=**2.3E+9 [eV/cm³/e]**0.6E+19 [e/As]1.6E-19 [J/ev]5.E-6 [A] =**11.E+3** [W/cm³].

- Estimate $dE/dzdt = \pi \varrho^2 dE/dVdt = 3.14 * 0.25^2 [cm^2] * 11.E+3 [W/cm^3] = 2.16 E+3 [W/cm].$
- From direct FLUKA "measurements " **dE/dzdt** = **2.54 E+3** [W/cm].

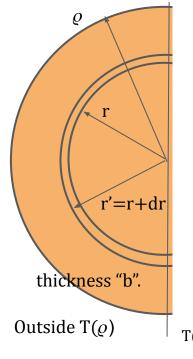
 $\Delta T = T(\varrho) - T(R) = (3.98*\frac{1}{2}*3.14)^{-1} [cm*K/W]*2.54E+3 [W/cm]*ln(25/0.25) = 1871 K, 2440 K for \frac{1}{4} coin.$

• For Long Magnet (3 m•0.1 T) and $\frac{1}{2}(2\pi)$ dE/dzdt is ~4 times lower => 240 K, for $\frac{1}{2}$ coins

and 120 K for full "coin".

- $T(\varrho) = 1815 \text{ C}$; reference magnet, $I = 5 \mu \text{A}$; T(R) = 35 C is maintained at r > R cm. How?
- $T(\varrho) = 1045 \text{ C}$; reference magnet, I=2.7 μ A.

Simple model for heating INSIDE the HOT SPOT. I=5 μ A of 12 GeV.



• In and out power for the $\frac{1}{4}$ o-ring (r, r'=r+dr):

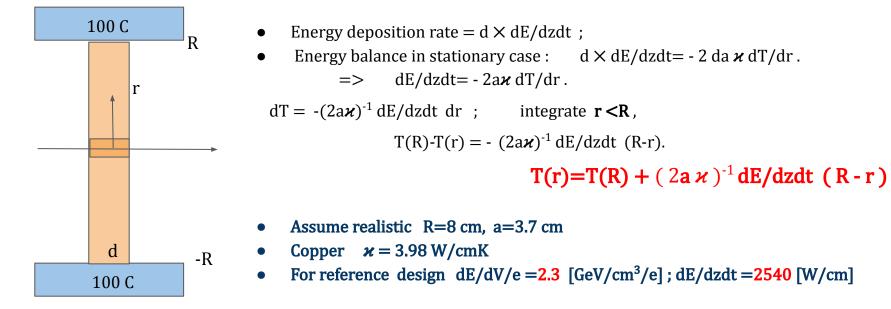
 $dE^+/dt = -\frac{1}{2}\pi r d\varkappa dT/dr$; $dE^-/dt = +\frac{1}{2}\pi r' d\varkappa dT/dr'$

• Energy balance for o-ring:

 $dE/dt = dE/dVdt \frac{1}{2} \pi b r dr = dE^+/dt (r) + dE^-/dt(r') = -\frac{1}{2} \pi b \varkappa dr d(r dT/dr)/dr$; $-dE/dVdt rdr = \varkappa d (r dT/dr)$; simplify and integrate r $-dE/dVdt \varkappa^{-1} \frac{1}{2}r^{2} + A = r (dT/dr);$ divide by r $dT/dr = Ar^{-1} - dE/(dVdt) \varkappa^{-1} \frac{1}{2}r$; what is A? From the previous slide $dT(\varrho)/dr = -\frac{1}{2} \rho \varkappa^{-1} dE/dV dt$; must be same; => A=0! $-dE/dVdt \varkappa^{-1}/_{2}r = dT/dr$ integrate ; $T(r) = B - dE/(dVdt) \varkappa^{-1} \frac{1}{4}(r^2 - \varrho^2)$; from the boundary condition $B = T(\varrho)$ $T(r) - T(\rho) = dE/dVdt \varkappa^{-1} (\rho^2 - r^2); T(r=0)?$ T(0)-T(ϱ) = $\frac{1}{4} (\pi \varkappa)^{-1} \pi \varrho^2 dE/dV dt = (3.98\pi)^{-1} [cm^*K/W] 2.54E+3 [W/cm] = 204 K;$ dE/dzdt = 2.54E+3 [W/cm] $T(0)=T(\rho)+204 K.$

- $T(\varrho) = 1815 C$ provided T(R) = 35 C temperature is maintained at R = 25 cm.
- T(0) = 2020 C in the center of HOT SPOT; reference design at $I = 5 \mu A$.
- T(0) = 1250 C in the center of HOT SPOT; reference design at $I = 2.7 \mu \text{A}$. 1140 C FEA, Hall-C.

Heating of Copper Bar by electron beam I=5 μ A, 12 GeV.



Bar d \times a \times 2R cm³

 $T(0)-T(R) = (2*3.7*3.98)^{-1} [K/W]*2.54E+3 [W/cm]*8 [cm] = 690 K.$ If no top/bott heat contact = 1380 K For 3m*0.1T magnet 4 times lower =170 K. T(0)=T(R) +690 K =790 K

• **Ref. Magnet.** T(0) = 990 C provided T(R)=300 C temperature is maintained at r > R cm via cooling !

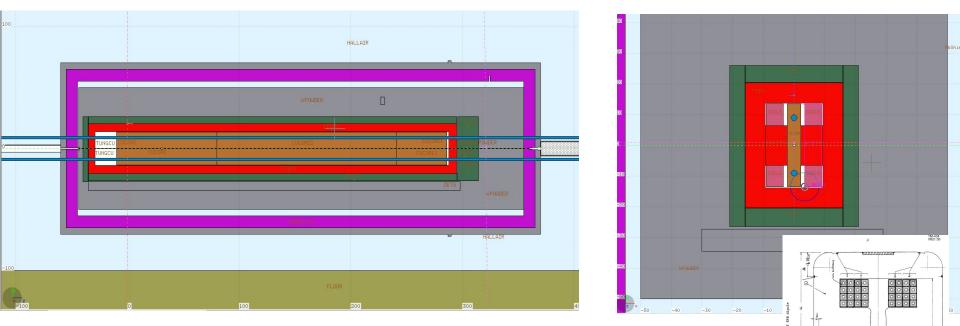
• Critical parameters for **reference design** are "a=a(z)" and "R=?". What should be T(R) to evacuate 50 kW? 7



III

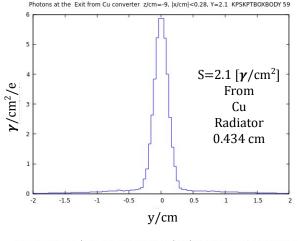
3 m Long Magnet Performance.

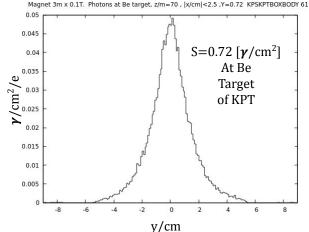
Magnet B=0.1 T × 3 m. Fermilab prototype 1.5 T × 3 m. Beam FWHM = 0.25 cm, Hole = 0.6×0.6 cm², Cu Converter t = 0.134 cm.

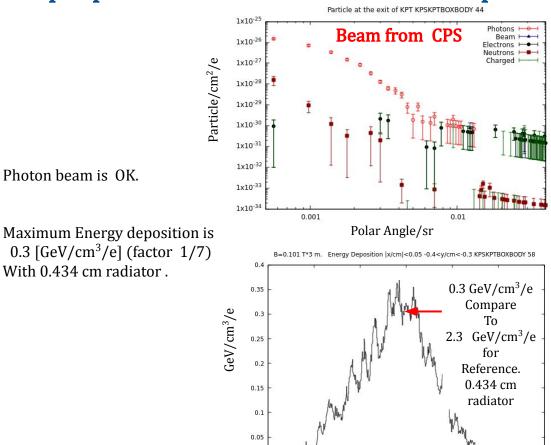


- Fermilab Magnet cooling provides 20 kW heat sink at maximum current.
- May be used at 10% of maximum current. Wider gap between poles?
- More room for cooling pipes through the Cu absorber; close to the hot spot.
- Thermal Contact between Cu Absorber and magnet poles and yoke ?

Photon Beam quality and Hot Spot power in CPS with $3 \text{ m} \times 0.1 \text{ T}$ Dipole.





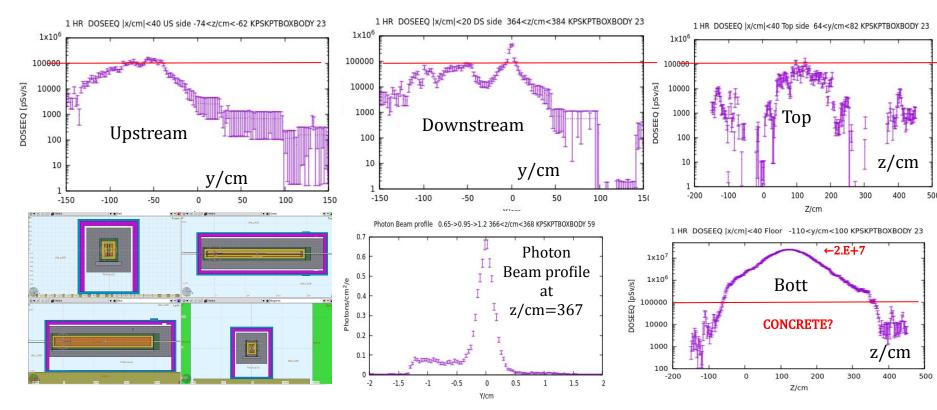


z/cm

300 10



Safety with 3m Dipole B=0.35 T (Fermilab prototype). Cu absorber. W shield. Concrete Floor. B=0.1 T in progress.





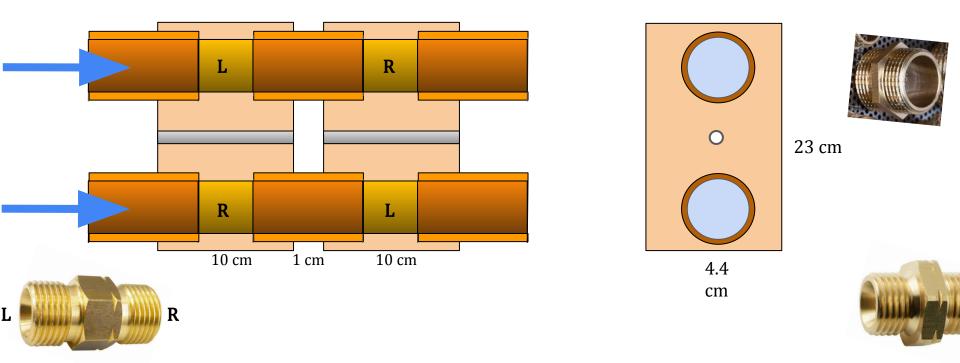
IV

3 m Long Magnet Cooling.

Copper absorber Cooling and Thermal Contact. How to make it good with cooling liquid.



Magnet $B=0.1 T \times 3 m$. Possible solution with Segmented Copper Absorber.



- 3m Ma_δ.. provides 4-7 times lower power in hot spot. Factor 0.25 in ΔT.
- Absorber of **uniform** × **section** 4 ×20 cm² with **round** beam **hole**; no problem of thermal contact between "top" and "bottom" parts. Factor 0.5 in ⊿T.
- **Direct contact to Cooling liquid** in each segment. Segments are connected by fittings with **left/right-**hand threads.
- Cooling water at v = 50 [cm/s] through the pipe S = 5 [cm²] evacuates 50 kW; 6 sec heating, C_v = 4184 J·kg⁻¹·K⁻¹.

Can we run our long CPS Absorber without cooling?

Consider Cu absorber, bar sized for $20 \times 5 \times 300 \text{ cm}^3$

Assume that Irradiation is the only way to evacuate the power P=50 kW.

$$\mathbf{P} = \boldsymbol{\epsilon} \, \boldsymbol{\sigma} \, \mathbf{S} \, \mathbf{T}^4$$

Where

 $\boldsymbol{\epsilon} = 1$; Emissivity; tabulated values for polished Cu: $\boldsymbol{\epsilon} = 0.04$; oxidized: $\boldsymbol{\epsilon} = 0.87$. $S = 1.5 [m^2]$; bar area. $\sigma = 5.7 \text{ E-8 } [W/m^2/K^4]$; Stefan-Boltzmann constant.

 $T = (50 [kW] / (5.7 \times 10^{-8} [W/m^2/K^4] \times 0.5 [m] \times 3 [m]))^{\frac{1}{4}} = 874 K = 600 C$; this surface T is required to irradiate 50 KW !

Surface temperature plus "T-gradient" in order to get T of the hot spot:

 $T = 874 \text{ K at } L = 300 \text{ cm}; \text{ In the hot spot } T = 600 \text{ C} + 340 \text{ C (gradient)} = ~940 \text{ C} ; \frac{1}{2} \text{ coin. cooling required } ! = ~770 \text{ C} ; \text{ slightly better for a full "coin".}$ $T = 1260 \text{ K at } L = 70 \text{ cm} \qquad T = ~1900 \text{ C} ; \text{ for reference design}$

Irradiation between two bodies:

$$P_{12} = \sigma S(T_1^4 - T_2^4) = 50 \text{ kW} = \sum T_2^4 + P_{12} / \epsilon_1 \sigma S = T_1^4 T_2^4 + 874^4 = T_1^4 T_1^4 = 877 \text{ K!} \text{ Has Almost NO effect!}$$

Can we cool down the Absorber? Risk estimate.

• Water speed required to evacuate 50 kW through a pipe d=3 cm, L=3 m, S=7 cm² $dE/dt=C_v(T_{out}-T_{in}) v S$; 5.E+4W =4.2 [JK⁻¹cm⁻³] 70 [K] 7 [cm²] v [cm/s]; we find:

v = 25 [cm/s].

- Heat transfer rate from absorber at T_a to liquid at $T_m = \frac{1}{2} (T_{out} T_{in})$ via area $A = 2 \pi d L = 6. E + 3 cm^2$ $dQ/dt = k (T_a - T_m) A$; must be 50 kW,
- Where k=4.E-2 [W cm⁻² K⁻¹] is "heat transfer coefficient"; empirical, tabulated value: $dQ/dt=k (T_a - T_m) A = 4. E-2 [Wcm^{-2} K^{-1}] 6. E+3 [cm^2] 250 [K]=50 kW.$
- That corresponds to absorber surface $T_a = 250 C + 50 C = 300 C$.
- We replace T(R) with $T_a = 300$ C to get the Hot Spot temperature (see slide 6, bar model): $T(0) = T_a + 170$ K = 470 C, if segments are a one piece doo.
- Water flow speed and heat flow looks consistent with our goal. No risk of melting.
- Model of absorber for FEA calculations is simple and should include irradiation (?)

Conclusive remarks

- There is a **high risk of overheating** for the reference design at 5 μ A.
- 3m magnet provides 4 times lower energy deposition on the hot spot. (Beam channel size?)
- This allows to keep the **hot spot temperature**:

 $\sim 470~C$ with Active Cooling System (Irradiation is not accounted yet).

~ 770 C with irradiation only.

- Unfortunately **active cooling** requires **~300 C temperature drop** between absorber and cooling liquid.
- **To be safe**: focus on **FEA analysis** of **3m Absorber** with Active Cooling System and Irradiation.